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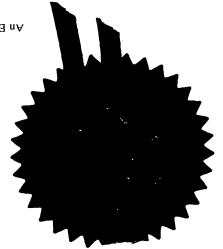
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Gas Delivery System

on a semiconductor wafer or the like. switched etch/deposition cycle or continuous process is used plasma processing apparatus, for example one in which a particularly, although not exclusively, one for use in a This invention relates to a gas delivery system,

active species in the process chamber resulting in improved process etch gases which allow an increase in the density of processes have led to the investigation of alternative The industry demands for higher etch rate . Yr ie imedo processes uses sulphur hexafluoride as the standard etch Dry process continuous and switched etch/deposition

process rates.

safe transportation and storage of the units. das generators contain a solid when cold and this allows for gases to high purity and at a reasonable cost and risk. chlorotrifluoride. They are able to generate the process generators include fluorine, nitrogen trifluoride bns ase₂ commercially available. peing made molten electrolyte gas generators have been reported and are the installation too hazardous. Latterly, a number of economics of implementing these chemistries extreme and/or commercial availability. These factors combine to make the increased cost, greater health and safety risks and poor candidates to enhance the process rate. All suffer from Several different chemistries are known to be likely

b) depositing a passivation layer on the surface of an

a) etching the substrate with a gas;

supply for a number of apparatuses.

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the chamber.

According to a third aspect of the present invention,

25 there is provided a method of treating a substrate

comprising cyclically performing the following steps:

According to a second aspect of the present invention, there is provided a method of treating a substrate comprising providing an etch and/or deposition gas to a chamber in which the substrate is situated, wherein the gas is delivered from a delivery system positioned locally to

"Locally" means that the delivery system is associated with a particular apparatus rather than being a central

Thus, according to a first aspect of the present invention there is provided an apparatus for treating a substrate, the apparatus comprising a chamber, a support for a substrate and delivery system for delivering an etching and/or deposition gas into the chamber, wherein the delivery system is positioned locally to the chamber.

The incorporation of these gas generators into a gas delivery system local to the process chamber allows a novel capability to introduce different processes gases into a variety of process schedules to achieve a process advantage. There are many novel aspects to the application of these gas generators to a dry processing environment in terms of generators to a dry processing environment in terms of system design, gas delivery control, system transportation, ease of installation and process advantages.

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delivery:

etched feature; and

etched feature, selectively removing the passivation layer from the

Indeed, the gases can be mixed with SF or other known trifluoride or chlorotrifluoride or mixtures thereof. wherein the etching gas comprises fluorine, nitrogen

gases.

Sgiecy issues compared to the conventional cylinder

eliminating the need for high pressure regulators on the pressure **STROSPACTIC** 4E oberate denerators

storage problems. The risks to operators are significantly SI until the user demands production eliminating hazardous There is no potentially hazardous gas in the system

constitution eliminating the risks of transporting the At room temperature the gas generators have a solid reduced.

hazardous gas on site or to the working location.

risks of hazardous gases in these pipes. from a centrail store on the installation and the associated The local delivery on demand eliminates long gas lines

Reduced cost of installation of the gas generators

installation to the processing environment. additional long gas lines from a central store on the The local delivery system eliminates the expense to add 52 compared to conventional cylinder delivery.

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The close proximity to the process equipment minimises typically comparable to the high pressure cylinders.

the safety precautions needed to protect the operator during

any maintenance operations.

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reatures of this novel use of the gas generators may

A totally dry method of heating the electrolyte instead

boreurislly extremely reactive but are separated by the the cathode of the electrolytic cell. The two gases are The gas generators produce a gas at both the anode and of the normal hot water bath.

design of the system to avoid any possible recombination.

atmospheric pressure. The gas generators are only designed to be operated at

the process chamber. This is an important design feature of that the generator does not see the low pressure (vacuum) at process chamber incorporates a novel control system such The design of the gas line to the

polish the generated gas to remove unwanted impurities Included in the local delivery system is the ability to the gas generators operation on the overall system.

It is envisaged that the invention can be used in our

Continuous operation dry processing (British Patent following co-pending applications:

Application No. 9805927.2). The gas generator can be used to

before passing into the process chamber.

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The production of the process gas from the generator is

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generated gas reacts spontaneously with the substrate. generate the reactive apecies or without a plasma where the This may involve the use of a plasma to process chamber. eupply a process gas to etch substrates placed in the

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squaurageously used to enhance the process etch rate either trifluoride пабохэти fluorine JO dya etch gas used in the switched plasma process. The generated allows the replacement or addition to the existing process 0822584 and EP-A-0822582). The addition of the generated gas Alternative gas for the switched plasma process (EP-A-

individually or in combination with the existing sulphur

Alternative gas for the plasma-less switched process

substrate, substitution of the sulphur hexafluoride process where the generated gas spontaneously reacts with the (British Patent Applications Nos. 9815931.2 and 9823364.6).

gas will also allow the operation of the process without

In addition, it is envisaged that the invention can be plasma in the process chamber.

used in the generation of gasea for a plasma/plasma-less

react with the substrate, allows the capability to introduce a plasma to produce the reactive species or spontaneously generate gases or combine gas mixtures which either require . 6. 4823364 Application Nos. 9815931.2 and 9823364.6. The ability to swiched process similar to that Patent British uŢ

a process schedule which may only require a plasma for one

or other of the process steps in the overall process

hexafluoride.

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